

Global Wire Bonder Equipment Market Study 2015-2025, by Segment (Ball bonders, Stud-bump bonders, Wedge bonders), by Market (Integrated Device Manufacturers (IDMs), Outsourced Semiconductor Assembly and Test (OSAT) Stud-bump bonders), by Company (ASM Pacific Technology, Kulicke& Soffa, Palomar Technologies)

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Abstracts

Snapshot

Wire bonder equipment is the machinery used for making interconnects between an IC or any other semiconductor device at the time of packaging. This interconnection ensures the flow of electricity in the semiconductor device. The thin-wire used to make these connections are usually made of copper, gold, aluminum, or silver. Wire bonder equipment is part of the semiconductor assembly and packaging process.

The global Wire Bonder Equipment market will reach xxx Million USD in 2018 and with a CAGR of xx% between 2019-2025.

Product Type Coverage (Market Size & Forecast, Major Company of Product Type etc.):

Ball bonders

Stud-bump bonders

Wedge bonders

Demand Coverage (Market Size & Forecast, Consumer Distribution):

Integrated Device Manufacturers (IDMs)

Outsourced Semiconductor Assembly and Test (OSAT)

Company Coverage (Sales data, Main Products & Services etc.):

ASM Pacific Technology

Kulicke& Soffa

Palomar Technologies

Besi

DIAS Automation

F&K Delvotec Bondtechnik

Hesse

Hybond

SHINKAWA Electric

Toray Engineering

West Bond

Major Region Market

North America

Europe

Asia-Pacific

South America

Middle East & Africa

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